(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

CORRECTED VERSION

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
24 January 2013 (24.01.2013)

WIPO | PCT

(10) International Publication Number
WO 2013/011372 A8

(51) International Patent Classification:
H01L 21/762 (2006.01)

(21) International Application Number:
PCT/IB2012/001406

(22) International Filing Date:
18 July 2012 (18.07.2012)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
1158331 20 September 2011 (20.09.2011) FR

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(81) Designated States *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ,

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(54) Title: METHOD FOR SEPARATING A LAYER FROM A COMPOSITE STRUCTURE

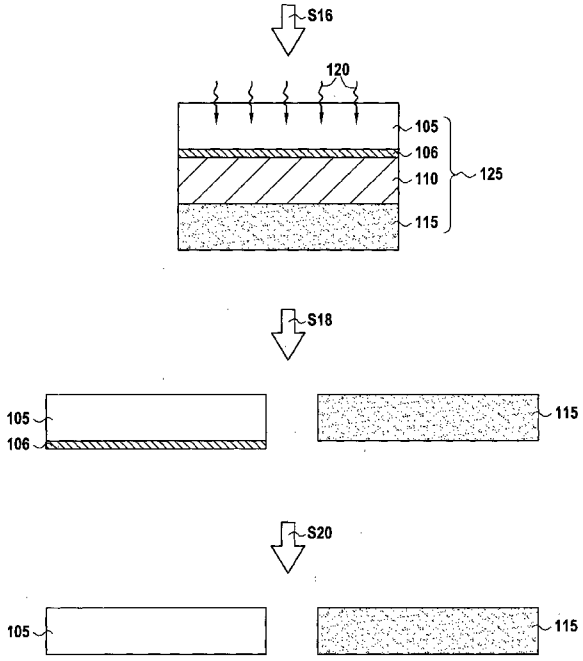


FIG.3B

(57) Abstract: The invention relates to a method for separating a layer (115) from a composite structure (125), the structure comprising a composite stack formed from at least a support substrate (105) which is partially transparent at a determined wavelength, the layer (115) to be separated and a separation layer (110) interposed between the support substrate and the layer to be separated, the method comprising irradiation of the separation layer (110) through the support substrate (105) by means of incident light ray (124a) at the determined wavelength in order to induce weakening or separation by exfoliation of the separation layer, the light ray being inclined so as to form an angle of incidence Θ such that $\theta > \theta_{min}$, where $\theta_{min} = \sin^{-1}(({}^{n}1/n_o)\sin(\tan^{-1}({}^{S}/_{2h})))$, n1 and n0 respectively being the refractive index of the support substrate and the refractive index of the external medium (130) in contact with the support substrate (105), from which the said ray comes, S being the width of the said ray and h being the thickness of the support substrate.

WO 2013/011372 A8

TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Declarations under Rule 4.17:

— *as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))*

— *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))*

— *of inventorship (Rule 4.17(iv))*

Published:

— *with international search report (Art. 21(3))*

(48) Date of publication of this corrected version:
24 April 2014

(15) Information about Correction:
see Notice of 24 April 2014